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(54) **THERMAL MODULE WITH A HYPERBARIC FAN SYSTEM FOR COOLING MULTIPLE FIN STACKS AND COMPONENTS IN A SEALED CHASSIS**

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ABSTRACT

A thermal module for cooling a plurality of component and cooling a bottom cover of a sealed chassis. A pair of fans are positioned in the chassis, wherein each fan has a first fan outlet directing a first portion of the airflow toward a first fin stack near a vent in the back cover, a second fan outlet for directing a second portion of the airflow to a second fin stack near a vent in a side cover, and a third fan outlet for directing a third portion of the airflow to a set of components in the chassis or a surface of the chassis. The size of each fan outlet and the size and impedance of the first fin stack and the second fin stack are configured to ensure the airflow is distributed according to a ratio based on cooling a set of components in the chassis and a bottom cover of the chassis.

